



S/N 10/723,474

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Suan J. Boon	Examiner:	DiLinh Nguyen
Serial No.:	10/723,474	Group Art Unit:	2814
Filed:	November 26, 2003	Docket No.:	303.601US2
Title:	ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING		

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
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Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on October 20, 2006. Please amend the above-identified patent application as follows.